



Semiconductor Device Type: D7X SOIC-16-0.150in-MatteTin			Package Homogeneous Materials							
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	3.33	(mg) Total	Die	% of Total Weight	0.75
Silicon	7440-21-3	Die	0.75	3.33	7531		Silicon	7440-21-3	100.00	
Copper	7440-50-8	Leadframe	27.29	120.66	272879		Total 100.00			
Iron	7439-89-6	Leadframe	0.66	2.91	6577					
Phosphorus	7723-14-0	Leadframe	0.01	0.04	84	124.97	(mg) Total	Leadframe	% of Total Weight	28.26
Zinc	7440-66-6	Leadframe	0.03	0.15	336		Copper	7440-50-8	96.55	
Silver	7440-22-4	Leadframe	0.28	1.22	2759		Iron	7439-89-6	2.33	
Epoxy Resin A	Trade secret	Die Attach	0.02	0.07	158		Phosphorus	7723-14-0	0.03	
Epoxy Resin B	Trade secret	Die Attach	0.01	0.04	90		Zinc	7440-66-6	0.12	
Silver	7440-22-4	Die Attach	0.17	0.77	1741		Silver	7440-22-4	0.98	
Polyoxypropylenediamine	Trade secret	Die Attach	0.01	0.04	90		Total 100.00			
Y-butyrolactone	96-48-0	Die Attach	0.01	0.04	90					
2,6-Diglycidyl phenyl allylether oligomer	Trade secret	Die Attach	0.01	0.04	90	1.00	(mg) Total	Die Attach	% of Total Weight	0.23
Gold	7440-57-5	Bonding Wire	0.36	1.57	3551		Epoxy Resin A	Trade secret	7.00	
Beryllium	7440-41-7	Bonding Wire	0.00	0.00	0		Epoxy Resin B	Trade secret	4.00	
Calcium	7440-70-2	Bonding Wire	0.00	0.00	0		Silver	7440-22-4	77.00	
Multi aromatic Resin	Trade Secret	Mold Compound	5.23	23.12	52300		Polyoxypropylenediamine	Trade secret	4.00	
Silica fused	60676-86-0	Mold Compound	59.97	265.16	599701		Y-butyrolactone	96-48-0	4.00	
Carbon Black	1333-86-4	Mold Compound	0.35	1.54	3487		2,6-Diglycidyl phenyl allyl ether oligomer	Trade secret	4.00	
Epoxy Cresol Novolac	29690-82	Mold Compound	1.39	6.17	13947		Total 100.00			
Phenol Resin	Trade secret	Mold Compound	2.79	12.33	27893					
Tin	7440-31-5	Lead Finish Plating	0.67	2.96	6694	1.57	(mg) Total	Bonding Wire	% of Total Weight	0.36
442.16 mg Total Mass			TOTALS:	100.00	442.16	1,000,000	Gold	7440-57-5	100.00	
							Beryllium	7440-41-7	0.00	
							Calcium	7440-70-2	0.00	
							Total 100.00			
						308.33	(mg) Total	Mold Compound	% of Total Weight	69.73
							Multi aromatic Resin	Trade Secret	7.50	
							Silica fused	60676-86-0	86.00	
							Carbon Black	1333-86-4	0.50	
							Epoxy Cresol Novolac	29690-82	2.00	
							Phenol Resin	Trade secret	4.00	
							Total 100.00			
						2.96	(mg) Total	Lead Finish Plating	% of Total Weight	0.67
						442.16	Tin	7440-31-5	100.00	100.00
							Total 100.00			

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